

# Investigation of the BiOi defect in EPI and Cz silicon diodes using Thermally Stimulated current (TSC) and Thermally Stimulated Capacitance (TS-Cap)



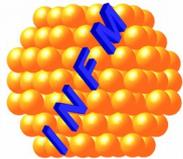
Chuan Liao<sup>a</sup>, E. Fretwurst<sup>a</sup>, E. Garutti<sup>a</sup>, J.Schwandt<sup>a</sup>

<sup>a</sup>Institut für Experimentalphysik, Universität Hamburg



A. Himmerlich<sup>b</sup>, Y. Gurimskaya<sup>b</sup>, I. Mateu<sup>b</sup>, M. Moll<sup>b</sup>

<sup>b</sup>Conseil européen pour la recherche nucléaire (CERN)



I. Pintilie<sup>c</sup>

<sup>c</sup>National Institute of Materials Physics (NIMP)



L. Makarenko<sup>d</sup>

<sup>d</sup>Belarussian State University



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I. Motivation

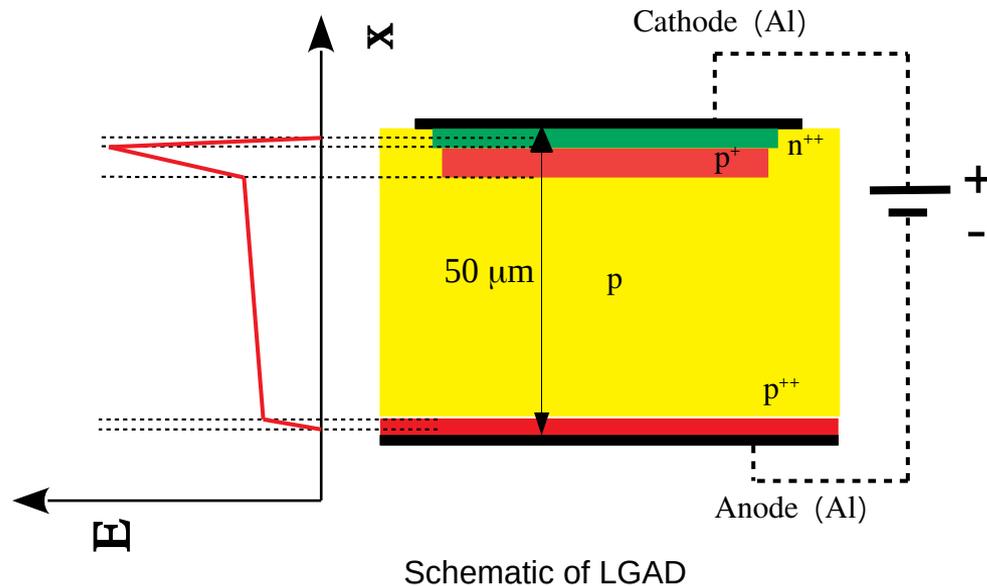
II. Experimental details

III. Measurements

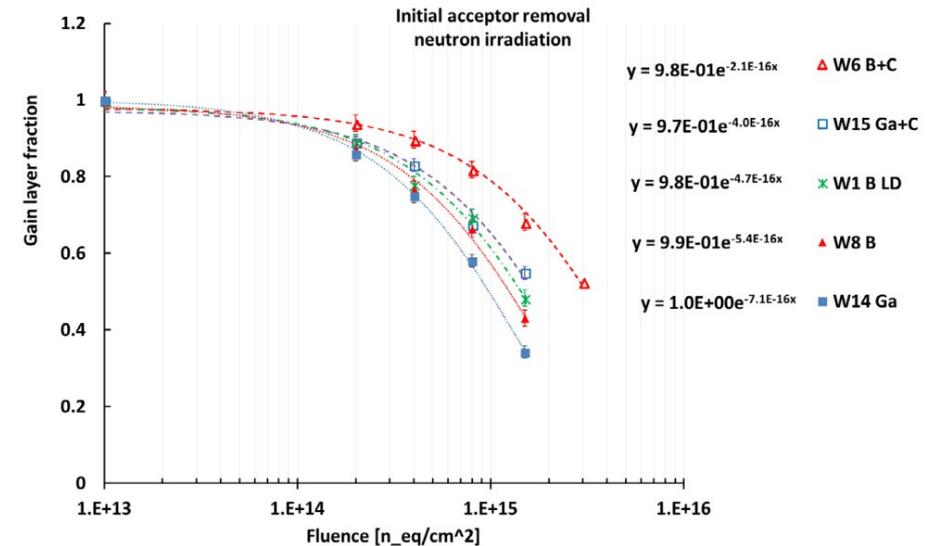
IV. Simulation

V. Summary

## Radiation damage of LGADs [1] (Low Gain Avalanche Diodes)



- Aluminum
- p type bulk (Boron doping,  $\sim 10^{13} \text{ cm}^{-3}$ )
- p<sup>+</sup> (Boron doping  $B_s^-$ ,  $\sim 10^{16} \text{ cm}^{-3}$ )
- p<sup>++</sup> (Boron doping  $B_s^-$ ,  $\sim 10^{19} \text{ cm}^{-3}$ )
- n<sup>++</sup> (phosphorus doping  $P_s^+$ ,  $\sim 10^{21} \text{ cm}^{-3}$ )



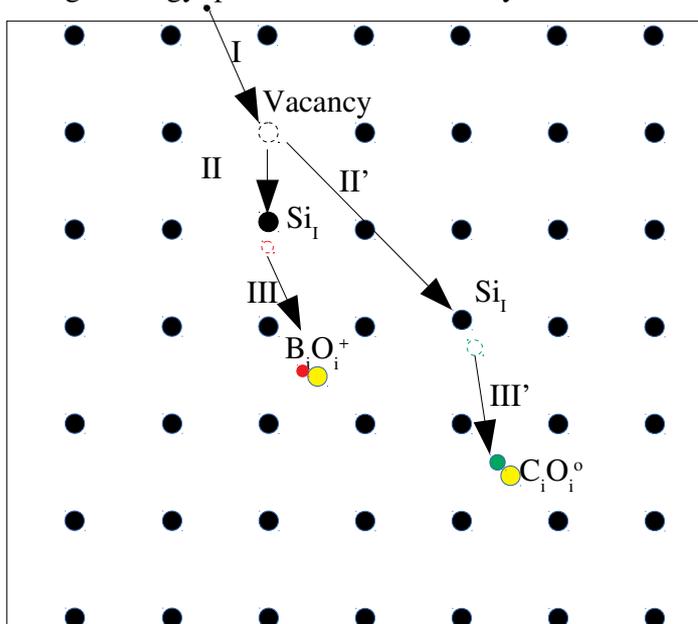
Gain fraction vs. Fluence for different doping

**Significant decrease of Gain value after irradiation**

[1] Kramberger, G., et al. "Radiation effects in Low Gain Avalanche Detectors after hadron irradiations." Journal of Instrumentation 10.07 (2015): P07006.

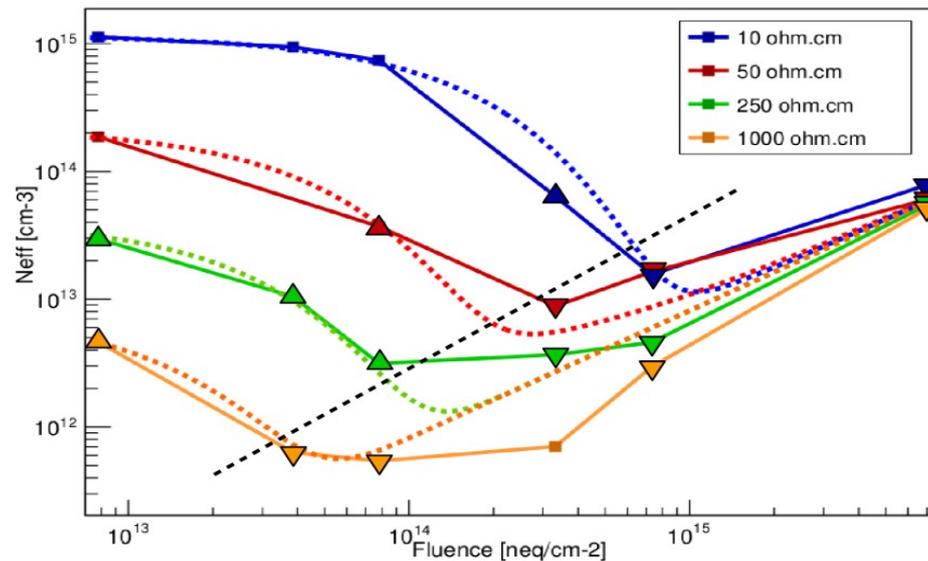
# Motivation

High energy particle or Gamma-ray



Schematic of radiation damage in p-type silicon material

- I: Lattice Silicon atom ( $\text{Si}_s$ ) is knocked out by incident particle and  $\text{Si}_s$  gets recoil energy and turns to interstitial silicon ( $\text{Si}_i$ )
- II:  $\text{Si}_i$  diffusion in the bulk and impact on Lattice Boron atom ( $\text{B}_s$ )
- III:  $\text{B}_s$  is knocked out by  $\text{Si}_i$  and turns to interstitial Boron ( $\text{B}_i$ ) and finally captured by interstitial Oxygen ( $\text{O}_i$ )



$N_{\text{eff}}$  vs. fluence for different initial doping concentration

Radiation damage of p-type diodes is dominated by acceptor removal in the beginning and afterwards by acceptor generation [1]

**$\text{B}^-$  turn to  $\text{B}_i\text{O}_i^+$**

Change in  $N_{\text{eff}}$  is a factor of 2 and it will significantly affect the distribution of electric field.

# Experimental details

## Information of measured silicon diodes

Label	EPI50P_06_DS_3	EPI50P_06_DS_7	EPI50P_06_DS_9	CZ300P_06_DS_3	CZ300P_06_DS_7
$N_{\text{eff},0}$	Expitaxial silicon, P-type $1.15 \times 10^{15} \text{ cm}^{-3}$			Cz silicon, P-type $1.05 \times 10^{15} \text{ cm}^{-3}$	
Initial resistivity	$\sim 10 \text{ } \Omega\text{cm}$			$\sim 10 \text{ } \Omega\text{cm}$	
Irradiation (6 MeV electrons)	$1 \times 10^{15} \text{ e/cm}^2$ ( $3.98 \times 10^{13} n_{\text{eq}}/\text{cm}^2$ )	$4 \times 10^{15} \text{ e/cm}^2$ ( $1.59 \times 10^{14} n_{\text{eq}}/\text{cm}^2$ )	$6 \times 10^{15} \text{ e/cm}^2$ ( $2.39 \times 10^{14} n_{\text{eq}}/\text{cm}^2$ )	$1 \times 10^{15} \text{ e/cm}^2$ ( $3.98 \times 10^{13} n_{\text{eq}}/\text{cm}^2$ )	$4 \times 10^{15} \text{ e/cm}^2$ ( $1.59 \times 10^{14} n_{\text{eq}}/\text{cm}^2$ )
Area	$6.21 \times 10^{-2} \text{ cm}^2$			$2.9 \times 10^{-2} \text{ cm}^2$	
Thickness	$50 \text{ } \mu\text{m}$			$350 \text{ } \mu\text{m}$	

C-V, I-V:



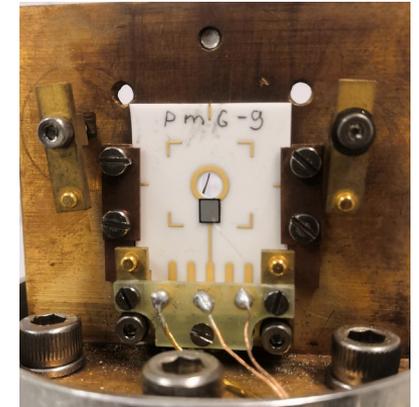
Experimental parameter (C-V, I-V):

Temperature:  $20 \text{ } ^\circ\text{C}$   
 Humidity:  $< 10\%$   
 Frequencies for C-V: 230 Hz, 455 Hz, 1 kHz, 10 kHz  
 AC voltage for C-V: 0.5 V

Experimental parameter (TSC and TS-Cap):

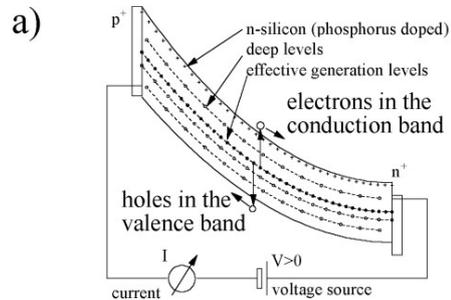
Cooling down bias: 0 V  
 Filling temperature: typical 10 K  
 Filling: Forward bias filling, 0 V filling or light injection  
 Filling time: 30 s  
 Delay time: 30 s  
 Heating rate:  $0.183 \text{ K/s}$

Thermally stimulated current and Thermally stimulated capacitance (TSC, TS-Cap):

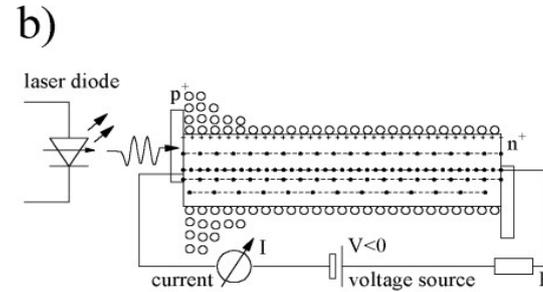


# Experimental details

## Basic Principle of Thermally Stimulated Current-TSC (or TS-Cap) [2]:

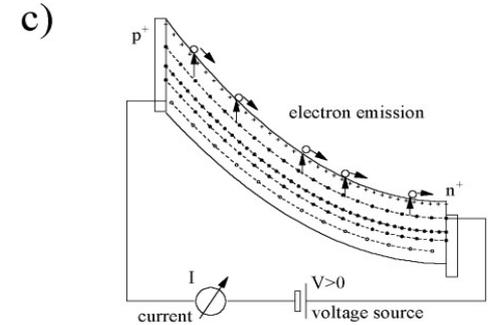


**a) Cooling**

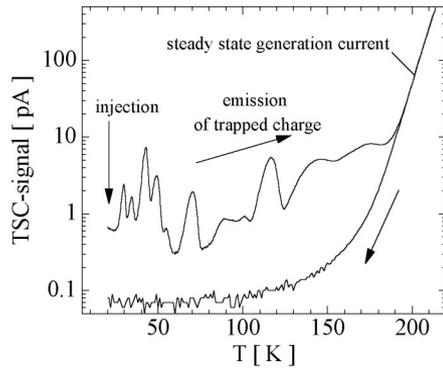


**b) Injection:**

Forward bias injection, light injection and majority carriers injection.



**c) Recording data**



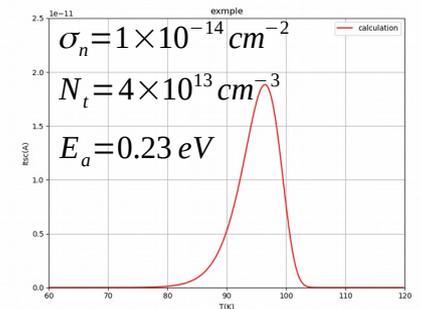
TSC spectrum [2]

$$I_{tsc} = \frac{1}{2} q_0 A d N_t e_n \exp\left(-\frac{1}{\beta} \int e_n(T) dT\right)$$

$$e_n = \sigma_n v_{th,n} N_c \times \exp\left(\frac{-E_a}{k_B T}\right)$$

$$E_a = E_C - E_T$$

$N_t$  is defect concentration;  $\beta$  is heating rate;  $\sigma_n$  is capture cross section;  $E_a$  is activation energy;  $A$  is diodes area;  $d$  depleted thickness; [1]

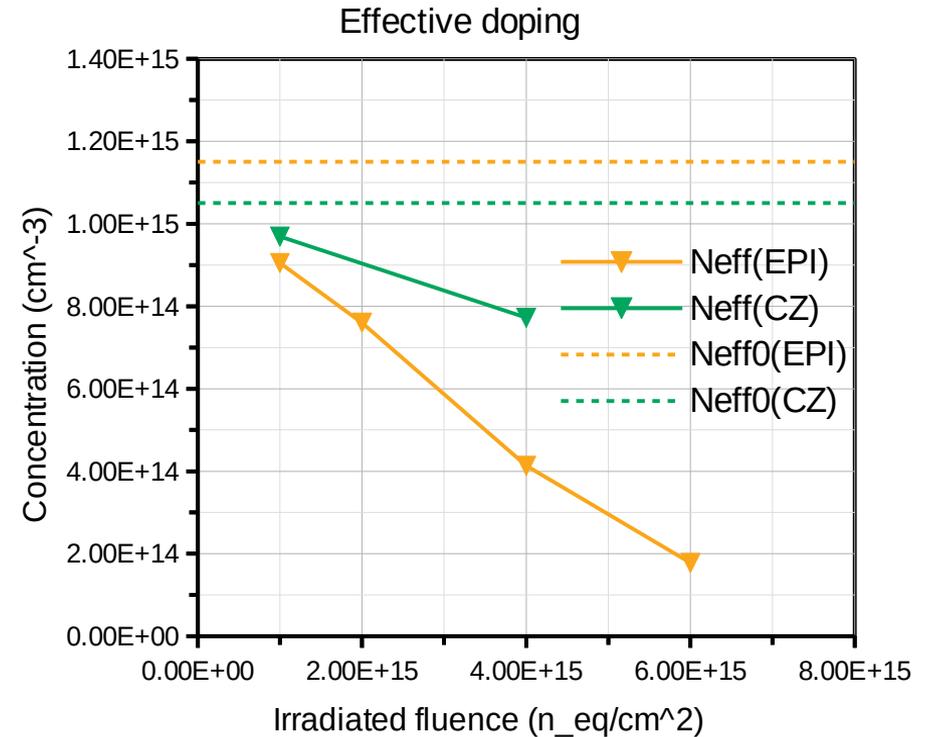
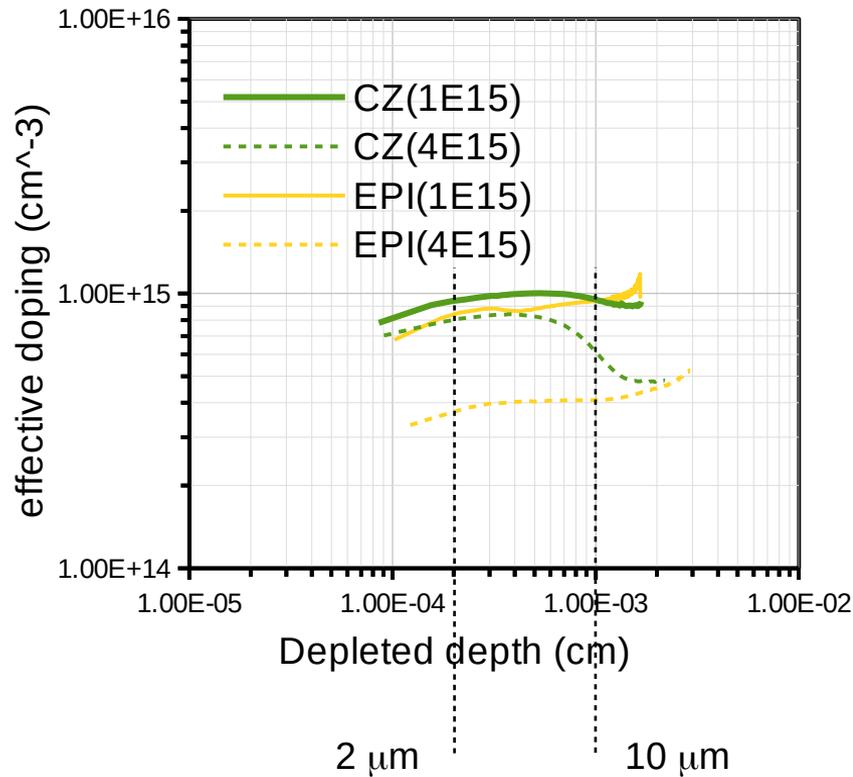


example of calculated TSC peak

[1] Buehler, M. G. Solid-State Electronics 15.1 (1972): 69-79.

[2] Moll, Michael. Radiation damage in silicon particle detectors: Microscopic defects and macroscopic properties. No. DESY-THESIS-1999-040. DESY, 1999.

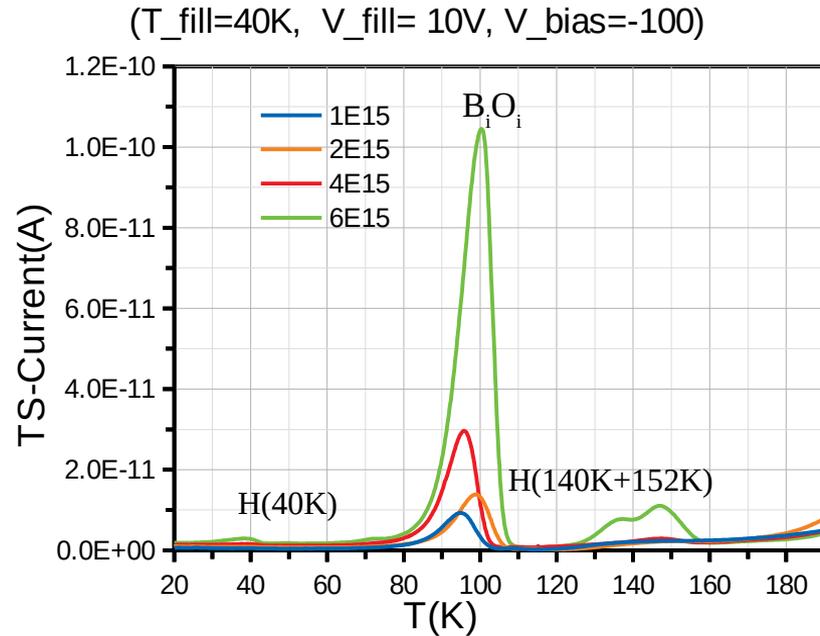
# $N_{\text{eff}}$ profile (10 $\Omega\text{cm}$ , as-irrad)



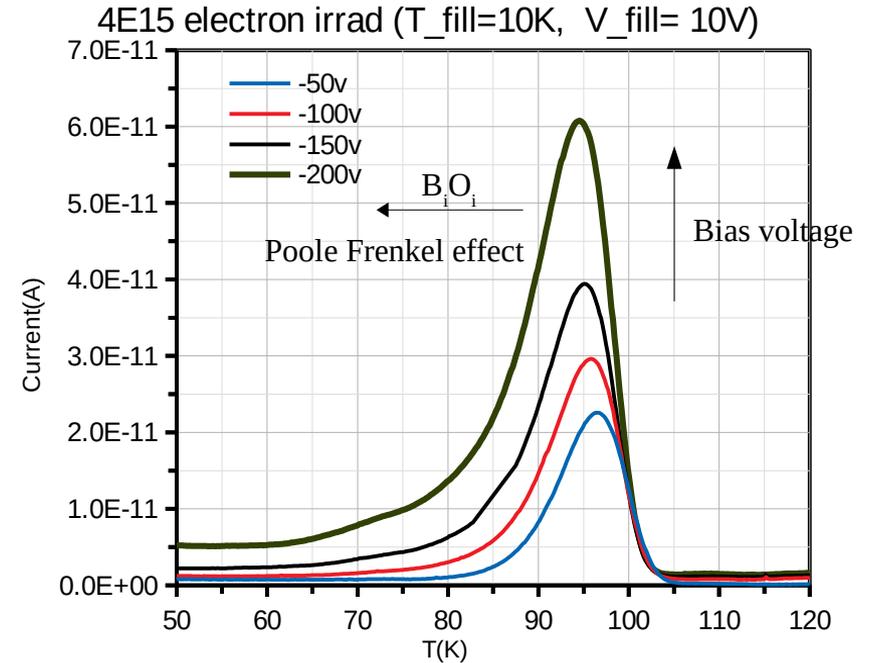
Doping profile for CZ and EPI diodes with fluence  $1\text{E}15$  and  $4\text{E}15$   $\text{e}/\text{cm}^2$ . (left figure)

Figure on the right: Decreases of the  $N_{\text{eff}}$  is smaller for CZ diodes compared to EPI devices (If edge effects can be ignored)

# Example of TSC on BiO<sub>i</sub> (10 Ωcm, as-irrad)



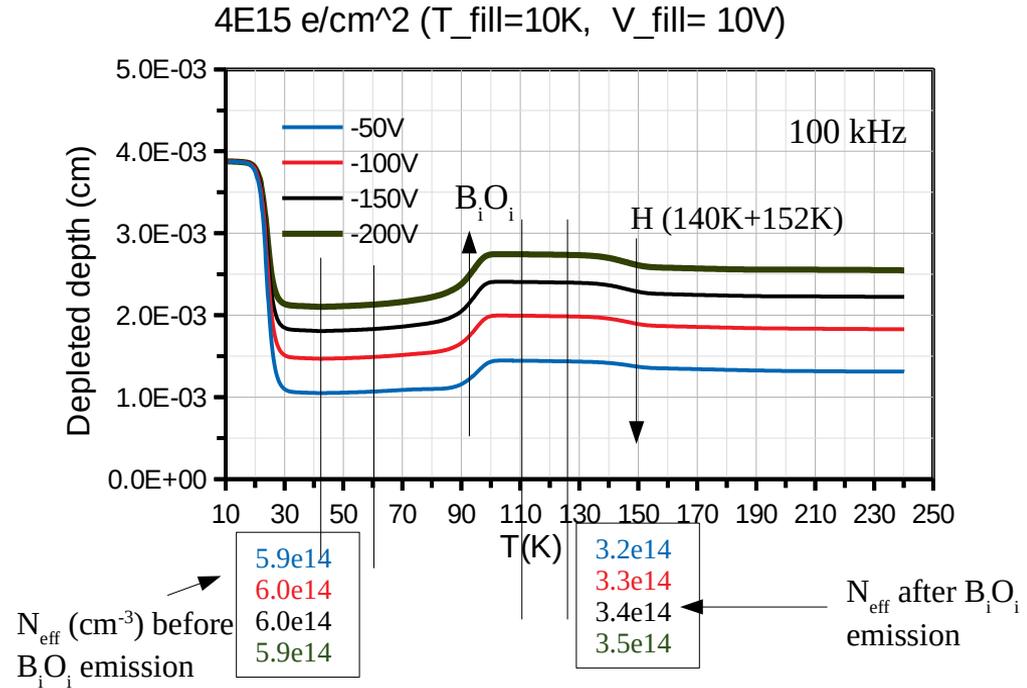
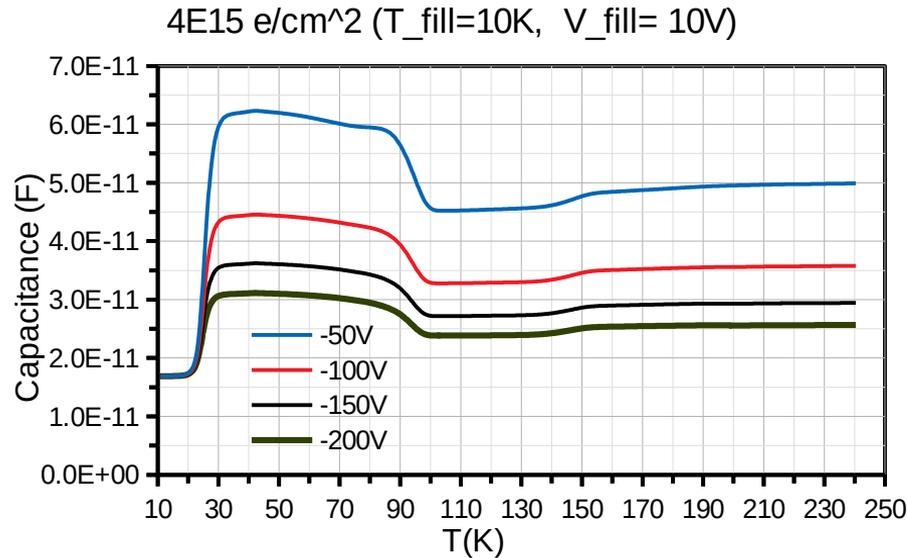
TSC spectra for diodes with different irradiation fluence



TSC spectra for different reverse bias heating up

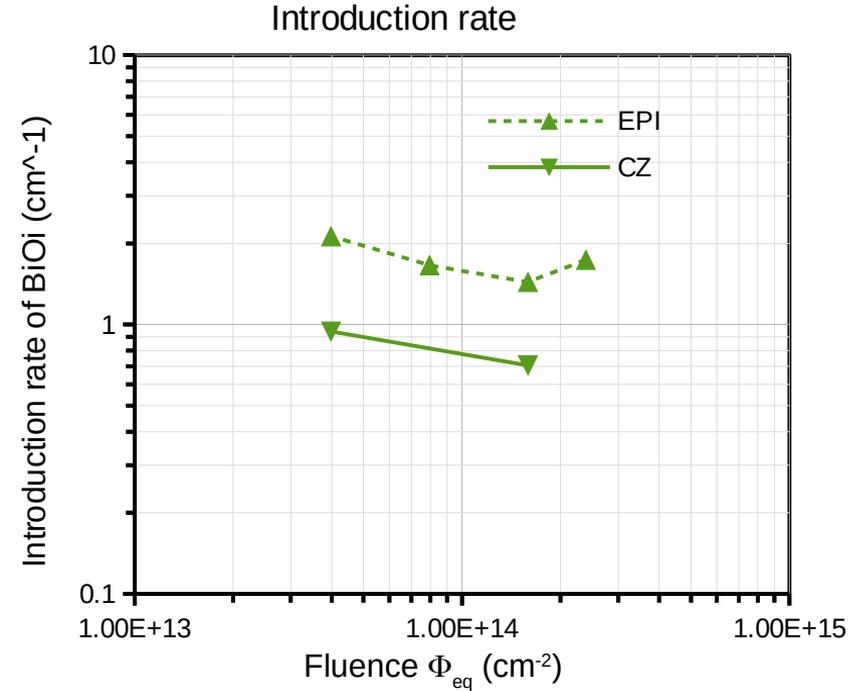
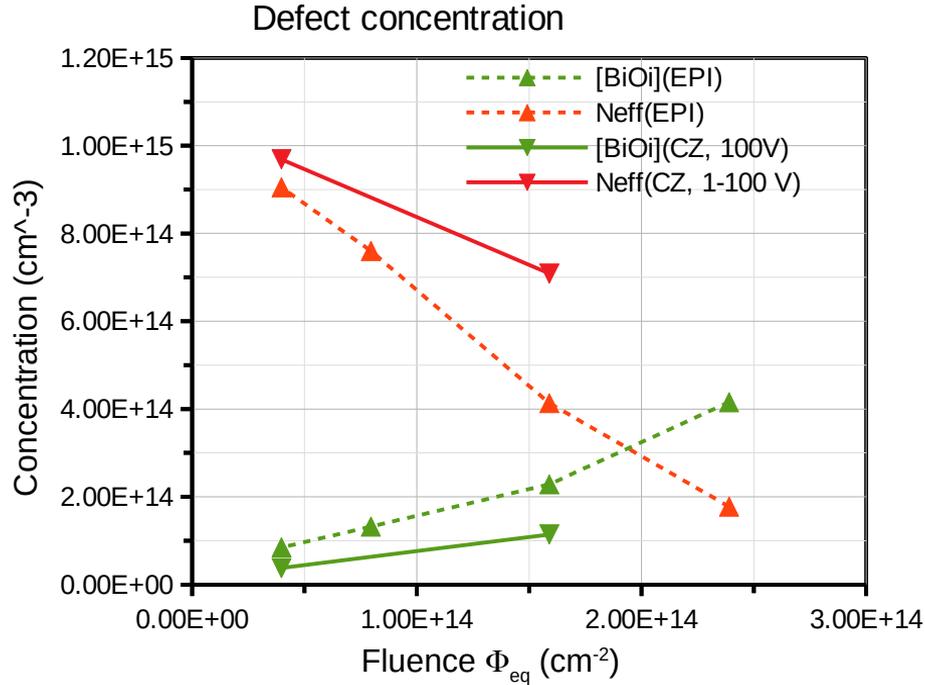
- Dominant BiO<sub>i</sub> signal, which depends on the fluence.
- Shift peak maximum with V<sub>bias</sub> → Poole-Frenkel effect; electron trap BiO<sub>i</sub> (o/+) donor defect
- Peak amplitude increases with bias voltage due to increasing depletion depth

# Example of TS-Cap on $B_iO_i$ ( $10 \Omega\text{cm}$ , as-irrad)



- Depleted depth was extracted from TS-cap with  $d = \epsilon_{\text{si}} \epsilon_0 A / C$
- The shift of  $B_iO_i$  peak temperature versus  $V_{\text{bias}}$  can also be observed in TS-Cap measurement
- Freeze-out of free charge carriers for  $T < 30 \text{ K}$
- Effective doping concentration can be extracted only if the diode is not fully depleted

# Defect concentration and introduction rate (as-irrad)



- $B_iO_i$  concentration of 1e15 diode and 2e15 diode are given by integration with constant depletion depth ( $w$ , which is given by C-V measurement) from 80 K to 110 K
- Defect concentration of 4e15 diode and 6e15 diode are given by the eq.(1) and sum from 80 K to 110 K.
- Effective doping ( $N_{eff}$ ) is extracted from doping profile

$$N_t(V) = \sum_i \frac{2Q_i}{q_0 A w(T_i)} \quad (1)$$

# Basic principle (1-D)

Poisson equation: 
$$\frac{dE}{dx} = \frac{q_0 N_{eff}}{\epsilon \epsilon_0}$$

Occupation fraction: 
$$f(T) = \exp\left(-\frac{1}{\beta} \int e_n dT\right)$$

Effective doping during emission:

$$N_{eff} = N_0 + N_t \cdot (1 - f(T))$$

3-d Poole Frenkel ( $\gamma = (qE/\pi\epsilon_0\epsilon_r)^{1/2}q/(k_B T)$ ):

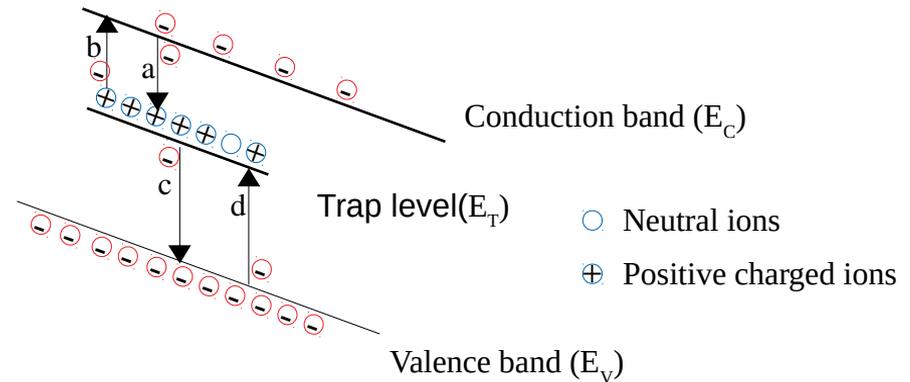
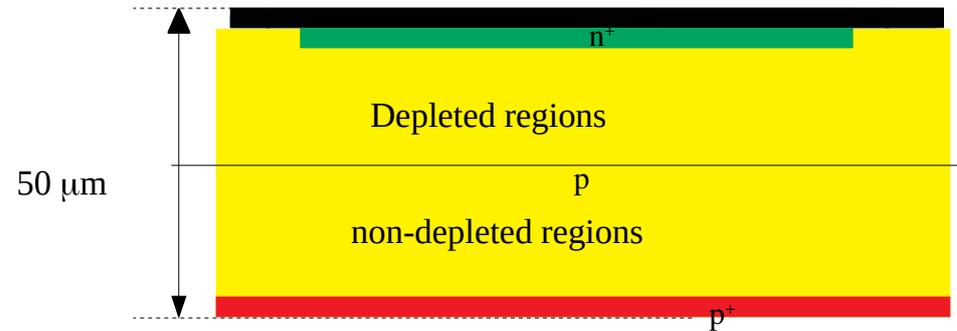
$$e_n = \sigma_n v_{th,n} N_c \times \exp\left(\frac{-Ea_0}{K_b T}\right) \left[\left(\frac{1}{\gamma^2}\right)(e^\gamma(\gamma-1)+1) + \frac{1}{2}\right]$$

TS-Capacitance:

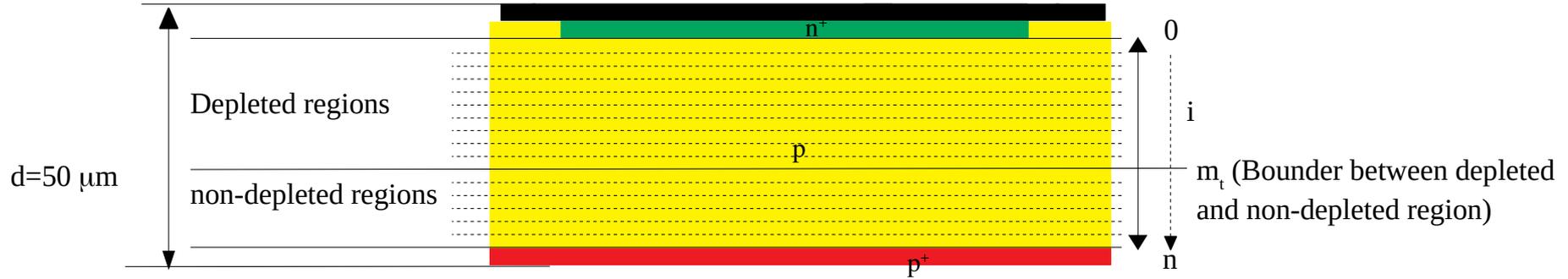
$$C = \frac{\epsilon \epsilon_0 A}{d(T)}$$

TS-Current:

$$I_{tsc} = q_0 A N_t \int_0^{d(T)} e_n f(T) \frac{d(T)-x}{d(T)} dx$$



# Finite element (Basic principle)



Occupation fraction:

$$f_{i,t} = \exp\left(-\sum_t e_{n,i,t}\right)$$

Simplification ( $t = \text{index for temperature } T_t(\text{K})$  in the region of interest,  $i$  stands for position):

Poisson equation ( $i < m_t$ ):

$$E_{i+1,t} - E_{i,t} = \frac{q_0 \text{Neff}_{i,t}}{\epsilon \epsilon_0} \cdot \frac{d}{n} \quad \text{and} \quad E_{i,t} = \sum_{i=0}^{m_t} \frac{q_0 \text{Neff}_{i,t}}{\epsilon \epsilon_0} \cdot \frac{d}{n} - \sum_{j=0}^i \frac{q_0 \text{Neff}_{j,t}}{\epsilon \epsilon_0} \cdot \frac{d}{n}$$

$$\sum_{i=0}^{m_t} E_{i,t} \cdot \frac{d}{n} = V$$

Effective doping during emission:

$$\text{Neff}_{i,t} = N_0 - N_t \cdot (1 - f_{i,t}) \quad N_t \text{ is defect concentration}$$

3-d Poole Frenkel ( $\gamma_{i,t} = (qE_{i,t} / \pi \epsilon_0 \epsilon_r)^{1/2} q / (k_B T_t)$ ):

$$e_{n,i,t} = \sigma_n v_{th,n} N_c \times \exp\left(\frac{-E_{a0}}{k_B T_t}\right) \left[\left(\frac{1}{\gamma_{i,t}^2}\right) (e^{\gamma_{i,t}} (\gamma_{i,t} - 1) + 1) + \frac{1}{2}\right]$$

$\sigma_n$  is capture cross section;  $v_{th,n}$  is thermal velocity of electron;  $N_c$  is state density on conduction band;  $E_{a0}$  is zero field activation energy;  $k_B$  is Boltzmann constant

# Simulation procedure (Matrix)

During emission 1 (example,  $t = 1$ ):

Emission ( $\gamma_{i,0} = (qE_{i,0}/\pi\epsilon_0\epsilon_r)^{1/2}q/(k_B T_0)$ ):

$$e_{n,i,1} = \sigma_n v_{th,n} N_c \times \exp\left(\frac{-E_{a0}}{k_B T_0}\right) \left[ \left(\frac{1}{\gamma_{i,0}}\right)^2 (e^{\gamma_{i,0}(\gamma_{i,0}-1)} + 1) + \frac{1}{2} \right]$$

$$f_{i,1} = \exp(-e_{n,i,0} + e_{n,i,1})$$

$$Neff_{i,1} = N_0 - N_t \cdot (1 - f_{i,1})$$

$$V = \left( \sum_0^{m_1} i \cdot \left( \frac{q_0 Neff_{i,1}}{\epsilon \epsilon_0} \cdot \frac{d}{n} \right) \right) \cdot \frac{d}{n}$$

$$E_{i,1} = \sum_0^{m_1} \frac{q_0 Neff_{i,1}}{\epsilon \epsilon_0} \cdot \frac{d}{n} - \sum_0^i \frac{q_0 Neff_{j,1}}{\epsilon \epsilon_0} \cdot \frac{d}{n}$$

$m_t$ :

0 ..... t

$m_0$			
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Electric field ( $E_{i,t}$ ):

0 ..... j ..... t

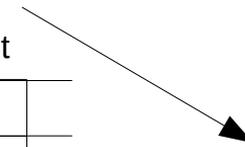
0	0		
$E_{0,0}$	$\Sigma q_0 Neff_{j,1} d / (\epsilon \epsilon_0 n)$		
$E_{1,0}$	$\Sigma q_0 Neff_{j,1} d / (\epsilon \epsilon_0 n) - q_0 Neff_{1,0} d / \epsilon \epsilon_0 n$		



Occupation fraction:

0 ..... t

0	$\exp(-(e_{n,0,0} + e_{n,0,1}))$		
1	$\exp(-(e_{n,1,0} + e_{n,1,1}))$		
2	$\exp(-(e_{n,2,0} + e_{n,2,1}))$		



Effective doping ( $Neff_{i,t}$ ):

0 ..... t

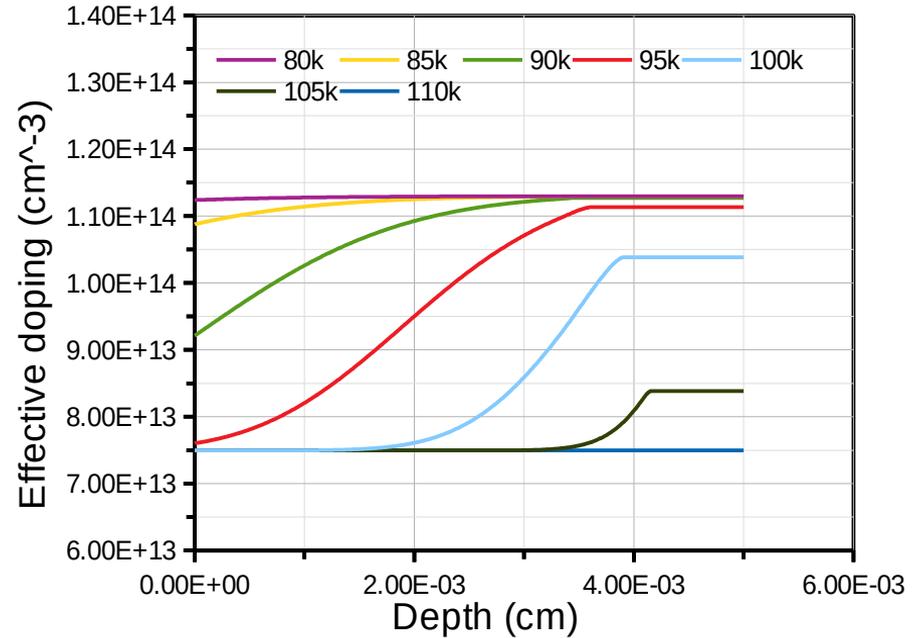
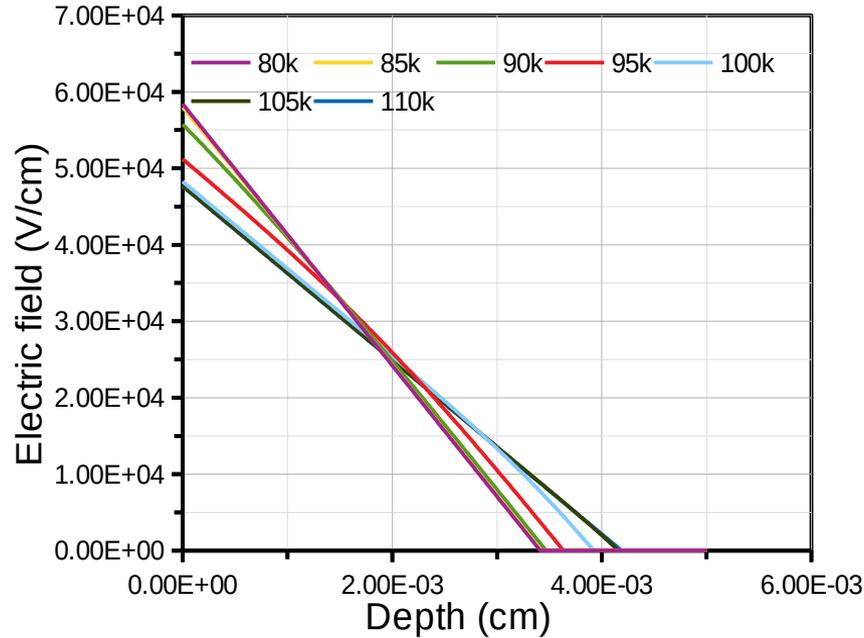
0	1.12964E14	$Neff_{0,1}$	
1	1.12964E14	$Neff_{1,1}$	
2	1.12964E14	$Neff_{2,1}$	

Emission rate:

0 ..... t

0	$e_{n,0,1}$		
1	$e_{n,1,1}$		
2	$e_{n,2,1}$		

# Electric field and Doping profile for $V_{\text{bias}} = -100\text{V}$

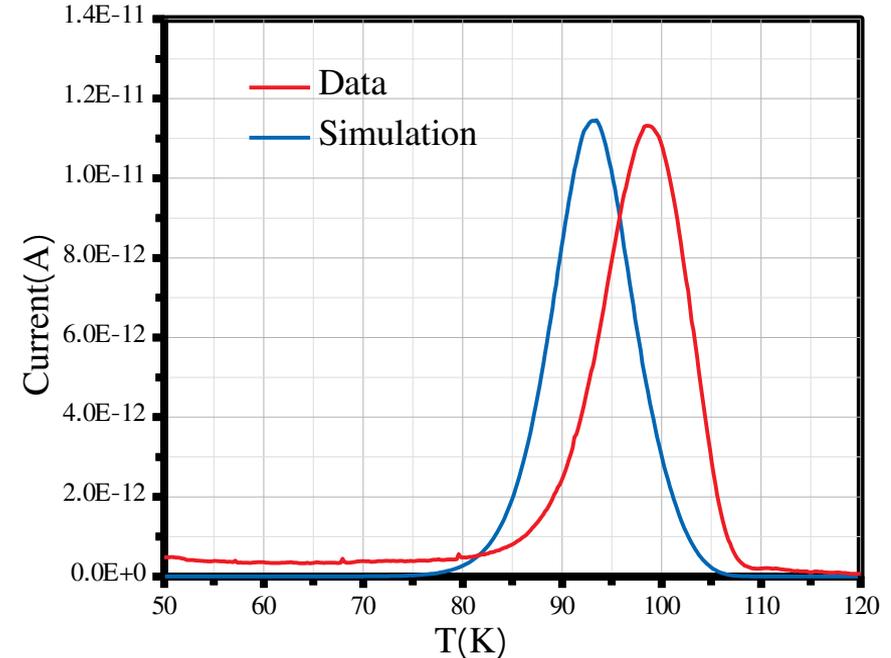
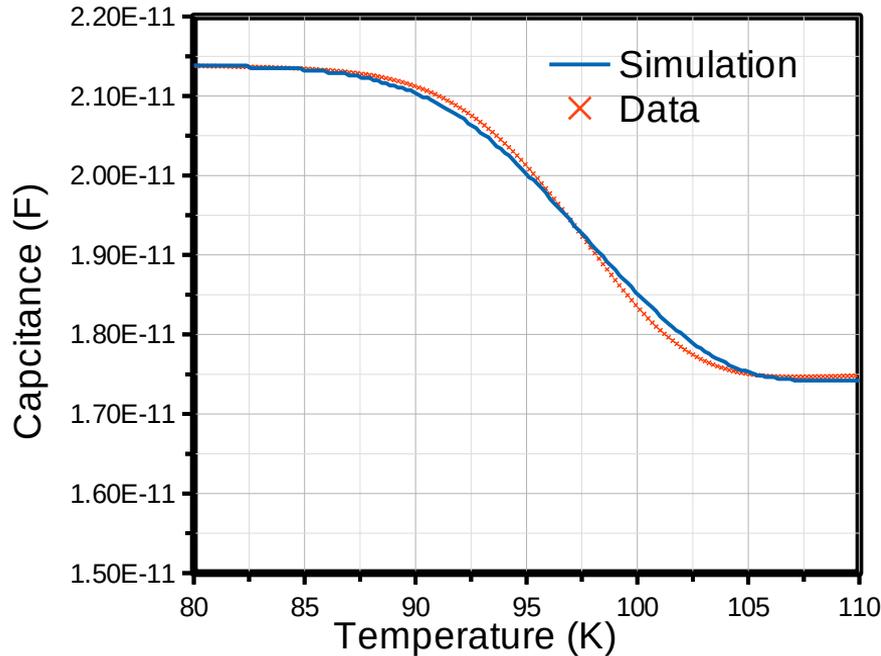


The distribution of electric field and doping profile for different temperatures. During  $\text{BiO}_i$  emission, the changes of electric field and doping profile is observed.

BiO<sub>i</sub> defect information:

$$\sigma_0 = 1\text{e-}14 \text{ cm}^2, E_{a0} = 0.269 \text{ eV}, N_t = 3.8\text{e+}13 \text{ cm}^{-3}, N_{\text{eff},0} = 1.13\text{e+}14 \text{ cm}^{-3}$$

# TS-Cap and TSC simulated and compared with data



Comparison of simulation and data for TS-Cap (left) and TSC spectrum (right). Possible reasons for the difference between simulation and data:

- Effect of non-depleted region

# Summary

I. Results for  $\sim 10 \Omega\text{cm}$  diodes irradiated by 6 MeV electron with fluence ( $1\text{e}15 \text{ e/cm}^2$ ,  $2\text{e}15 \text{ e/cm}^2$ ,  $4\text{e}15 \text{ e/cm}^2$  and  $6\text{e}15 \text{ e/cm}^2$ ):

a). Macroscopic measurement (C-V):

- Effective doping decreases as fluence increases

b). Microscopic measurement (TSC, TS-Cap):

- $\text{B}_i\text{O}_i$  peak on TSC spectra: 3-D Poole Frenkel effect (shift with bias voltage)
- $\text{B}_i\text{O}_i$  concentration proportional to irradiated fluence
- $\text{B}_i\text{O}_i$  introduction rate ( $g_{\text{BiO}_i}$ ) is nearly the same for the different fluence values
- **Different  $\text{B}_i\text{O}_i$  concentration extracted from TSC and TS-Cap**

c). The comparison of CZ and EPI diodes:

- Cz material shows smaller decrease of  $N_{\text{eff}}$  and lower BiOi concentration compared to EPI material for the same fluence

II. Results of simulation:

- Considering the Poole Frenkel effect, the changes of electric field and doping profile has been simulated
- The simulated TS-Cap values agree quite well with the experimental data. The small differences between simulation and experiment might due to an effect from non-depleted region
- The difference between the simulated and measured TSC spectrum is quite large. This finding has to be investigated further in more detail.